



## Material Content Data Sheet



<b>Sales Product Name</b>		1EDI05112AF		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001245996						
<b>Package</b>		PG-DSO-8-51		<b>Weight*</b>		80.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.899	2.36	2.36	23648	23648
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		411	
	non noble metal	iron	7439-89-6	0.660	0.82		8214	
wire	non noble metal	copper	7440-50-8	26.789	33.35	34.22	333541	342269
	noble metal	gold	7440-57-5	0.231	0.29	0.29	2875	2875
	encapsulation	organic material	carbon black	1333-86-4	0.147	0.18		1832
encapsulation	plastics	epoxy resin	-	4.758	5.92		59240	
	inorganic material	silicondioxide	60676-86-0	44.147	54.98	61.08	549646	610718
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10133	10133
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1186	1186
glue	plastics	acrylic resin	-	0.162	0.20		2018	
	noble metal	silver	7440-22-4	0.575	0.72	0.92	7153	9171
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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